

BUK9Y19-55B

N-channel TrenchMOS logic level FET Rev. 03 — 29 February 2008

Product data sheet

Product profile

1.1 General description

Logic level N-channel enhancement mode power Field-Effect Transistor (FET) in a plastic package using Nexperia High-Performance Automotive (HPA) TrenchMOS technology. This product has been designed and qualified to the appropriate AEC standard for use in automotive critical applications.

1.2 Features

- 175 °C rated
- Q101 compliant

- Logic level compatible
- Very low on-state resistance

1.3 Applications

- 12 V and 24 V loads
- General purpose power switching
- Automotive systems
- Motors, lamps and solenoids

1.4 Quick reference data

Table 1. **Quick reference**

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
I_D	drain current	$V_{GS} = 5 \text{ V}; T_{mb} = 25 \text{ °C};$ see <u>Figure 1</u> and <u>4</u>	-	-	46	Α
P _{tot}	total power dissipation	T _{mb} = 25 °C; see <u>Figure 2</u>	-	-	85	W
Static ch	aracteristics					
R _{DSon}	drain-source on-state resistance	$V_{GS} = 5 \text{ V}; I_D = 20 \text{ A};$ $T_j = 25 \text{ °C}; \text{ see } \frac{\text{Figure } 12}{13} \text{ and } \frac{13}{13}$	-	16.3	19	mΩ
Avalanch	ne ruggedness					
E _{DS(AL)S}	non-repetitive drain-source avalanche energy	$\begin{split} I_D &= 46 \text{ A; } V_{sup} \leq 55 \text{ V;} \\ R_{GS} &= 50 \Omega; V_{GS} = 5 \text{ V;} \\ T_{j(init)} &= 25 ^{\circ}\text{C; } unclamped \end{split}$	-	-	80	mJ



2. Pinning information

Table 2. Pinning

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	S	source	mb	D
2	S	source		
3	S	source		$G \longrightarrow \overline{A}$
4	G	gate		
mb	D	mounting base; connected to drain	₩ ₩ ₩ ₩ ₩ ₩ ₩ ₩ ₩ ₩ ₩ ₩ ₩ ₩ ₩ ₩ ₩ ₩ ₩	mbb076 S

3. Ordering information

Table 3. Ordering information

Type number	Package	kage						
	Name	Description	Version					
BUK9Y19-55B	LFPAK	plastic single-ended surface-mounted package (LFPAK); 4 leads	SOT669					

4. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DS}	drain-source voltage	$T_j \ge 25 ^{\circ}C; T_j \le 175 ^{\circ}C$	-	55	V
V_{DGR}	drain-gate voltage	$R_{GS} = 20 \text{ k}\Omega$	-	55	V
V_{GS}	gate-source voltage		-15	15	V
I _D	drain current	$T_{mb} = 25 ^{\circ}C; V_{GS} = 5 V; \text{ see } \frac{\text{Figure 1}}{} \text{ and } \frac{4}{}$	-	46	Α
		$T_{mb} = 100 ^{\circ}\text{C}; V_{GS} = 5 \text{V}; \text{see} \frac{\text{Figure 1}}{}$	-	32	Α
I_{DM}	peak drain current	T_{mb} = 25 °C; $t_p \le 10 \mu s$; pulsed; see Figure 4	-	184	Α
P _{tot}	total power dissipation	T _{mb} = 25 °C; see <u>Figure 2</u>	-	85	W
T _{stg}	storage temperature		-55	175	°C
Tj	junction temperature		-55	175	°C
Avalanci	he ruggedness				
E _{DS(AL)S}	non-repetitive drain-source avalanche energy	$I_D = 46 \text{ A; } V_{sup} \leq 55 \text{ V; } R_{GS} = 50 \Omega; V_{GS} = 5 \text{ V; } \\ T_{j(init)} = 25 ^{\circ}\text{C; unclamped}$	-	80	mJ
E _{DS(AL)R}	repetitive drain-source avalanche energy	see <u>Figure 3</u>	[1][2] - [3]	-	J
Source-	drain diode				
I _S	source current	T _{mb} = 25 °C	-	46	Α
I _{SM}	peak source current	$t_p \le 10 \ \mu s$; pulsed; $T_{mb} = 25 \ ^{\circ}C$	-	184	Α

^[1] Single-pulse avalanche rating limited by maximum junction temperature of 175 °C.

^[2] Repetitive avalanche rating limited by average junction temperature of 170 °C.

^[3] Refer to application note AN10273 for further information.

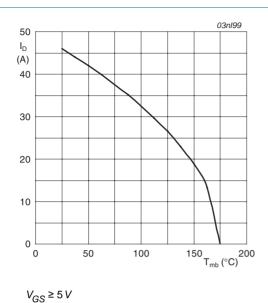
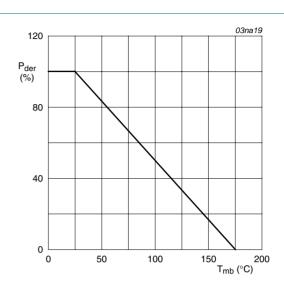
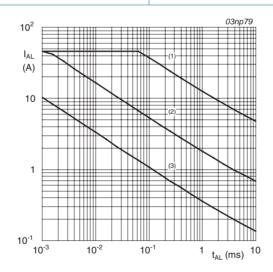


Fig 1. Continuous drain current as a function of mounting base temperature



$$P_{der} = \frac{P_{tot}}{P_{tot(25^{\circ}C)}} \times 100 \%$$

Fig 2. Normalized total power dissipation as a function of mounting base temperature



- (1) Single-pulse; $T_i = 25 \, ^{\circ}C$.
- (2) Single-pulse; $T_i = 150 \, ^{\circ}\text{C}$.
- (3) Repetitive.

Fig 3. Single-shot and repetitive avalanche rating; avalanche current as a function of avalanche period

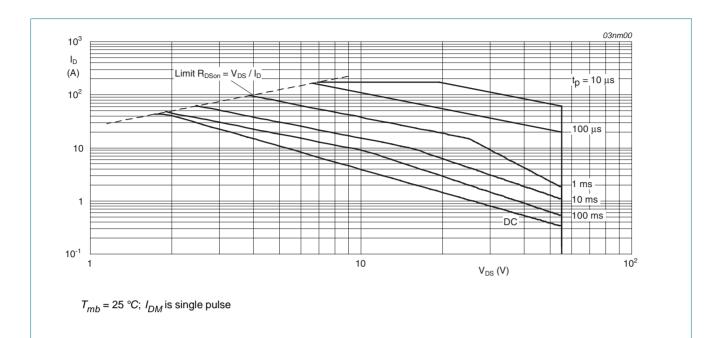


Fig 4. Safe operating area; continuous and peak drain currents as a function of drain-source voltage

5. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	see Figure 5	-	-	1.8	K/W

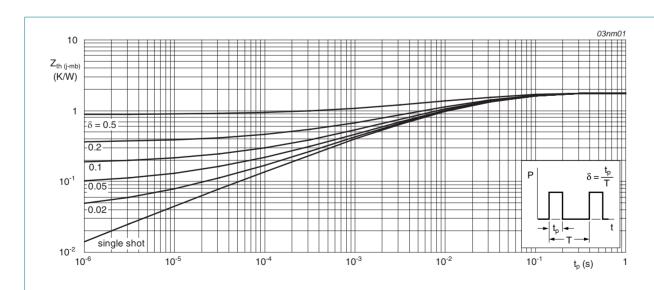
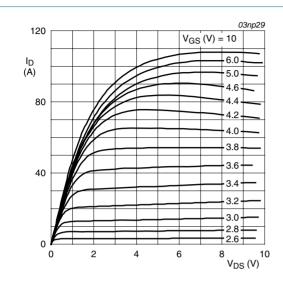


Fig 5. Transient thermal impedance from junction to mounting base as a function of pulse duration

6. Characteristics

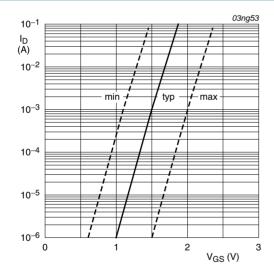
Table 6. Characteristics

Table 6.	Characteristics					
Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Static cha	racteristics					
$V_{(BR)DSS}$	drain-source breakdown voltage	$I_D = 0.25 \text{ mA}; V_{GS} = 0 \text{ V};$ $T_j = 25 ^{\circ}\text{C}$	55	-	-	V
		$I_D = 0.25 \text{ mA}; V_{GS} = 0 \text{ V};$ $T_j = -55 \text{ °C}$	50	-	-	V
$V_{GS(th)}$	gate-source threshold voltage	$I_D = 1$ mA; $V_{DS} = V_{GS}$; $T_j = -55$ °C; see <u>Figure 11</u>	-	-	2.3	V
		$I_D = 1 \text{ mA}$; $V_{DS} = V_{GS}$; $T_j = 25 \text{ °C}$; see Figure 11	1.1	1.5	2	V
		$I_D = 1 \text{ mA}; V_{DS} = V_{GS};$ $T_j = 175 ^{\circ}\text{C}; \text{see } \frac{\text{Figure } 11}{\text{Figure } 11}$	0.5	-	-	V
I _{DSS}	drain leakage current	$V_{DS} = 55 \text{ V}; V_{GS} = 0 \text{ V};$ $T_j = 175 ^{\circ}\text{C}$	-	-	500	μА
		V_{DS} = 55 V; V_{GS} = 0 V; T_j = 25 °C	-	0.02	1	μΑ
I_{GSS}	gate leakage current	V_{DS} = 0 V; V_{GS} = 15 V; T_j = 25 °C	-	2	100	nA
		$V_{DS} = 0 \text{ V}; V_{GS} = -15 \text{ V};$ $T_j = 25 ^{\circ}\text{C}$	-	2	100	nA
R_{DSon}	R _{DSon} drain-source on-state	V_{GS} = 4.5 V; I_D = 20 A; T_j = 25 °C	-	-	21	$m\Omega$
	resistance	$V_{GS} = 10 \text{ V}; I_D = 20 \text{ A}; T_j = 25 ^{\circ}\text{C}$	-	14.3	17.3	mΩ
		$V_{GS} = 5 \text{ V}; I_D = 20 \text{ A}; T_j = 25 ^{\circ}\text{C};$ see Figure 12 and 13	-	16.3	19	mΩ
		$V_{GS} = 5 \text{ V; } I_D = 20 \text{ A; } T_j = 175 \text{ °C;}$ see <u>Figure 12</u> and <u>13</u>	-	-	40	mΩ
Source-d	rain diode					
V_{SD}	source-drain voltage	$I_S = 25 \text{ A}; V_{GS} = 0 \text{ V}; T_j = 25 ^{\circ}\text{C};$ see Figure 16	-	0.85	1.2	V
t _{rr}	reverse recovery time	$I_S = 20 \text{ A}; dI_S/dt = -100 \text{ A/}\mu\text{s};$	-	52	-	ns
Q _r	recovered charge	$V_{GS} = -10 \text{ V}; V_{DS} = 30 \text{ V};$ $T_j = 25 \text{ °C}$	-	38	-	nC
Dynamic	characteristics					
Q _{G(tot)}	total gate charge	$I_D = 25 \text{ A}; V_{DS} = 44 \text{ V}; V_{GS} = 5 \text{ V};$	-	18	-	nC
Q_{GS}	gate-source charge	T _j = 25 °C; see <u>Figure 14</u>	-	5	-	nC
Q_{GD}	gate-drain charge		-	8	-	nC
C _{iss}	input capacitance	$V_{GS} = 0 \text{ V}; V_{DS} = 25 \text{ V};$	-	1494	1992	pF
C _{oss}	output capacitance	f = 1 MHz; T _j = 25 °C; see Figure 15	-	217	260	pF
C _{rss}	reverse transfer capacitance		-	86	118	pF
t _{d(on)}	turn-on delay time	$V_{DS} = 30 \text{ V}; R_L = 1.2 \Omega;$	-	18	-	ns
t _r	rise time	V_{GS} = 5 V; $R_{G(ext)}$ = 10 Ω; T_i = 25 °C	-	180	-	ns
t _{d(off)}	turn-off delay time	1, - 20 0	-	44	-	ns
t _f	fall time		-	134	-	ns



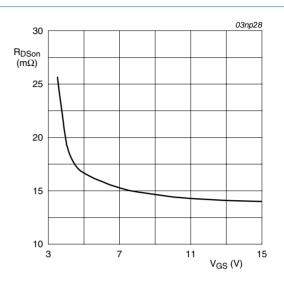
 $T_j = 25 \, ^{\circ}C; t_p = 300 \, \mu s$

Fig 6. Output characteristics: drain current as a function of drain-source voltage; typical values



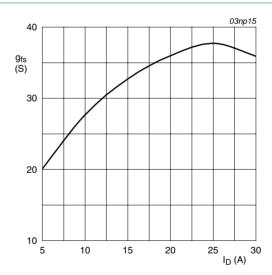
 $T_j = 25$ °C; $V_{DS} = V_{GS}$

Fig 8. Sub-threshold drain current as a function of gate-source voltage



$$T_i = 25 \, ^{\circ}C; I_D = 20 \, A$$

Fig 7. Drain-source on-state resistance as a function of gate-source voltage; typical values



$$T_i = 25 \, ^{\circ}C; V_{DS} = 25 \, V$$

Fig 9. Forward transconductance as a function of drain current; typical values

6 of 12

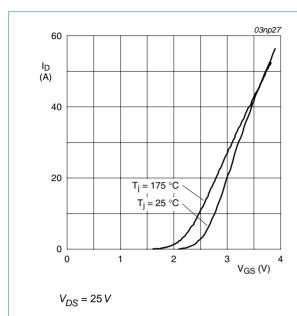


Fig 10. Transfer characteristics: drain current as a function of gate-source voltage; typical values

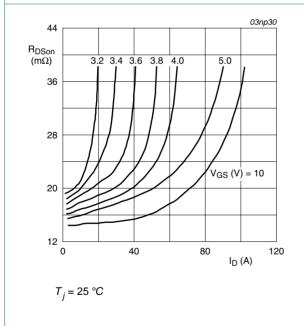
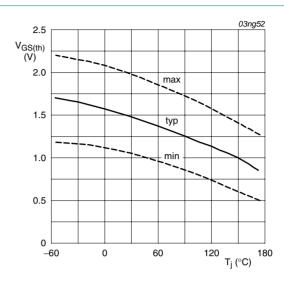


Fig 12. Drain-source on-state resistance as a function of drain current; typical values



$$I_D = 1 \, mA; V_{DS} = V_{GS}$$

Fig 11. Gate-source threshold voltage as a function of junction temperature

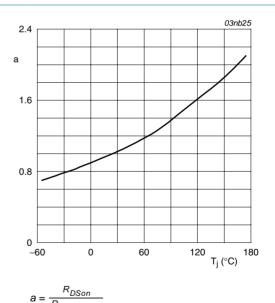
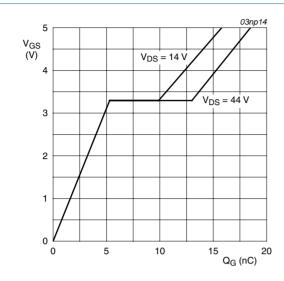


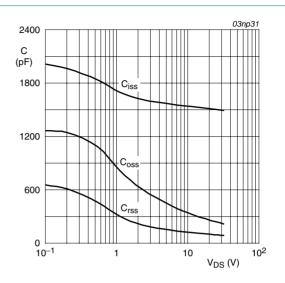
Fig 13. Normalized drain-source on-state resistance factor as a function of junction temperature

7 of 12



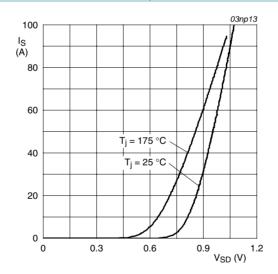
 $T_j = 25 \text{ °C}; I_D = 25 \text{ A}$

Fig 14. Gate-source voltage as a function of gate charge; typical values



$$V_{GS} = 0 V; f = 1 MHz$$

Fig 15. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values



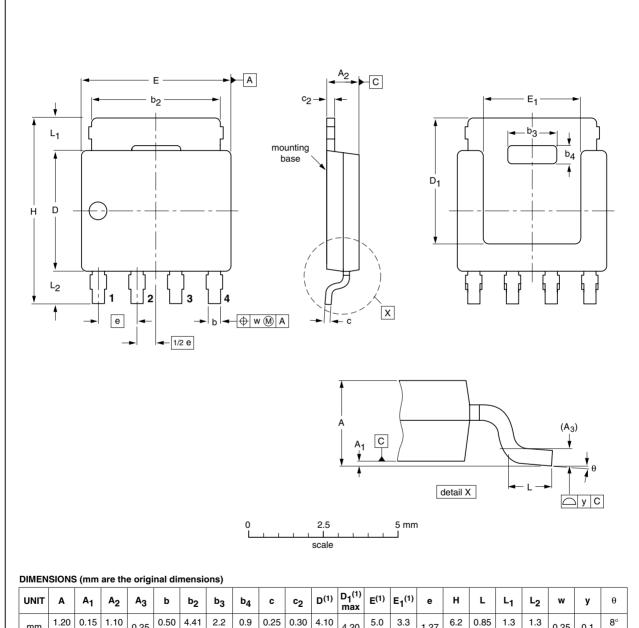
 $V_{GS} = 0 V$

Fig 16. Source current as a function of source-drain voltage; typical values

Package outline

Plastic single-ended surface-mounted package (LFPAK); 4 leads

SOT669



UNIT	A	A ₁	A ₂	A ₃	b	b ₂	b ₃	b ₄	С	c ₂	D ⁽¹⁾	D ₁ ⁽¹⁾ max	E ⁽¹⁾	E ₁ ⁽¹⁾	е	Н	L	L ₁	L ₂	w	у	θ
mm	1.20 1.01	0.15 0.00	1.10 0.95	0.25	0.50 0.35	4.41 3.62	2.2 2.0	0.9 0.7	0.25 0.19	0.30 0.24		4.20	5.0 4.8	3.3 3.1	1.27	6.2 5.8	0.85 0.40	1.3 0.8	1.3 0.8	0.25	0.1	8° 0°

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE		REFER	RENCES	EUROPEAN	ISSUE DATE	
VERSION	IEC	JEDEC	JEITA	PROJECTION	13302 DATE	
SOT669		MO-235			04-10-13 06-03-16	

Fig 17. Package outline SOT669 (LFPAK)

N-channel TrenchMOS logic level FET

8. Revision history

Table 7. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BUK9Y19-55B_3	20080229	Product data sheet	-	BUK9Y19-55B_2
Modifications:	guidelines	of this data sheet has been of NXP Semiconductors. have been adapted to the r		·
BUK9Y19-55B_2	20060411	Product data sheet	-	BUK9Y19-55B-01
BUK9Y19-55B-01	20040528	Product data sheet	_	

9. Legal information

9.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions"
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N-channel TrenchMOS logic level FET

11. Contents

1	Product profile
1.1	General description
1.2	Features
1.3	Applications
1.4	Quick reference data 1
2	Pinning information
3	Ordering information
4	Limiting values
5	Thermal characteristics 4
6	Characteristics 5
7	Package outline 9
8	Revision history
9	Legal information11
9.1	Data sheet status
9.2	Definitions
9.3	Disclaimers
9.4	Trademarks 11
10	Contact information
44	Contents 13

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